General Description

The MAX6575L/H is a low-cost, low-current temperature sensor with a single-wire digital interface. It features accuracy of $\pm 3^{\circ}$ C at $+25^{\circ}$ C, $\pm 4.5^{\circ}$ C at $+85^{\circ}$ C, and $\pm 5^{\circ}$ C at $+125^{\circ}$ C. The MAX6575L/H is a monostable, externally triggered temperature sensor that allows a microprocessor (µP) to interface with up to eight temperature sensors using a single control line. Temperatures are sensed by measuring the time delay between the falling edge of the external triggering pulse and the falling edge of the subsequent pulse delays reported from the devices. Different sensors on the same I/O line use different timeout multipliers to avoid overlapping signals.

The MAX6575L/H features eight different timeout multipliers; these are selectable by using the two time-select pins on each device and choosing the "L" or "H" version. The "L" version provides four delay ranges less than 50ms. The "H" version provides four delay ranges greater than 50ms. The MAX6575L/H is available in a space-saving 6-pin SOT23 package.

Applications

Critical µP and µC Temperature Monitoring Portable Battery-Powered Equipment Cell Phones Battery Packs Hard Drives/Tape Drives Networking and Telecom Equipment Medical Equipment Automotive

Features

- Simple Single-Wire Interface to μP or μC
- Multidrop up to Eight Sensors on One Wire
- ±0.8°C Accuracy at +25°C (±3°C max)
- Operates from +2.7V to +5.5V Supply Voltage
- Low 150µA (typ) Supply Current
- Standard Operating Temperature Range: -40°C to +125°C
- Small 6-Pin SOT23 Package

Ordering Information

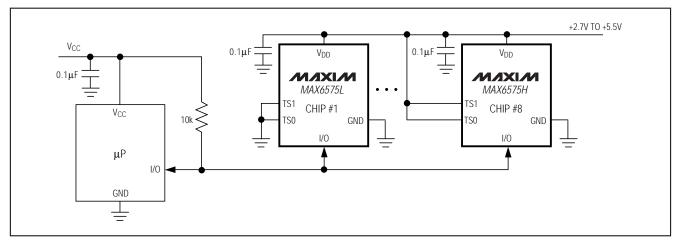
PART	TEMP. RANGE	PIN- PACKAGE	SOT TOP MARK
MAX6575LZUT	-40°C to +125°C	6 SOT23	AABG
MAX6575HZUT	-40°C to +125°C	6 SOT23	AABH

_Selector Guide

PART	TIMEOUT MULTIPLIERS (µs/°K)
MAX6575L	5, 20, 40, 80
MAX6575H	160, 320, 480, 640

Pin Configurations appear at end of data sheet.

Typical Operating Circuit



M/IXI/M

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ABSOLUTE MAXIMUM RATINGS

Terminal Voltage (with respect to GND)

MAX6575L/H

reminal voltage (minrespect to GND)	
V _{DD}	0.3V to +6V
TS1, TS0	-0.3V to (V _{DD} + 0.3V)
Ι/Ο	0.3V to +6V
Input/Output Current, All Pins	±20mA

Continuous Power Dissipation ($T_A = +70^{\circ}C$)	
6-Pin SOT23 (derate 7.10mW/°C above +70	°C)571mW
Operating Temperature Range	40°C to +125°C
Storage Temperature Range	
Lead Temperature (soldering, 10sec)	+300°C

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS

 $(V_{DD} = +2.7V \text{ to } +5.5V, T_A = -40^{\circ}\text{C} \text{ to } +125^{\circ}\text{C}, \text{ unless otherwise noted}. Typical values are specified at T_A = +25^{\circ}\text{C} \text{ and } V_{DD} = +5V, unless otherwise noted.}$

PARAMETER	SYMBOL		CONDITIONS	MIN	TYP	MAX	UNITS
V _{DD} Range	Vdd			2.7		5.5	V
Supply Current	1		$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$		150	250	
Supply Current	IDD	$V_{DD} = 5.5V$	$T_{A} = -40^{\circ}C \text{ to } +125^{\circ}C$			400	μA
		T _A = -20°C	1	-7.5	±1.1	+7.5	
T 1 0 F		$T_A = 0^{\circ}C$		-5.5	±0.9	+5.5	
Temperature Sensor Error (Note 1)		$T_A = +25^{\circ}C$		-3.0	±0.8	+3.0	°C
		$T_A = +85^{\circ}C$		-4.5	±0.5	+4.5	
		$T_A = +125^{\circ}C$		-5.0	±0.5	+5.0	
	tD1		VTS1 = GND, VTS0 = GND		5T		
	t _{D2}	MAX6575L, T (temp) in °K,	V _{TS1} = GND, V _{TS0} = V _{DD}		20T		
	t _{D3}	Figure 1	V _{TS1} = V _{DD} , V _{TS0} = GND		40T		
Output Pulse Delay	tD4		VTS1 = VDD, VTS0 = VDD		80T		ЦĊ
Oulput Fulse Delay	t _{D5}	MAX6575H, T (temp) in °K,	V _{TS1} = GND, V _{TS0} = GND		160T		- µs
	tD6		V _{TS1} = GND, V _{TS0} = V _{DD}		320T		
	t _{D7}	Figure 1	V _{TS1} = V _{DD} , V _{TS0} = GND		480T		
	tD8		VTS1 = VDD, VTS0 = VDD		640T		
Output Pulse Low Time	t _{L1-8}	Figure 1			5T		μs
Reset Pulse Width (Note 2)	treset	Figure 1		4.6		16.0	ms
Setup Time	t SETUP	Figure 1			10		μs
Start Pulse (Note 3)	t START	Figure 1, TA = +	25°C	2.5			μs
Delay Time from Trigger to Ready (Note 4)	t _{READY}	Figure 1				520	ms
Glitch Immunity on I/O Input					500		ns
Time Calent Dia Leasie Levela	VIL					0.8	N
Time-Select Pin Logic Levels	VIH			2.3			V
	Mai	$V_{DD} > 4.5V$, I_{SIN}	к = 3.2mA			0.4	V
I/O Output Voltage Low	Vol	V _{DD} > 2.7V, I _{SIN}	к = 1.2mA			0.3	V
I/O Input Voltage Low	VIL					0.8	V
I/O Input Voltage High	VIH			2.3			V

Note 1: See Temperature Accuracy histograms in Typical Operating Characteristics.

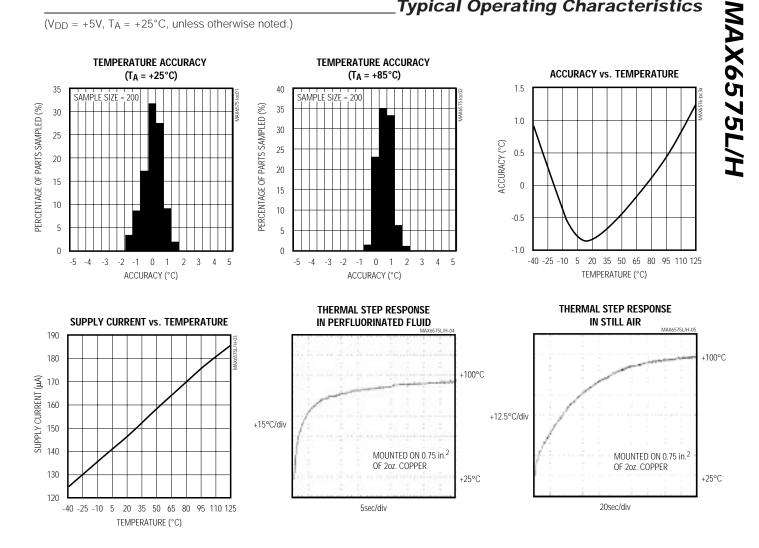
Note 2: Guaranteed by design. Not production tested.

Note 3: Limit maximum start pulse at 1ms to avoid timing overlap.

Note 4: If no reset pulse is applied.

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Typical Operating Characteristics

Pin Description

PIN	NAME	FUNCTION
1	V _{DD}	Positive Supply Voltage
2	GND	Ground
3	N.C.	No Connect. Connect pin to GND or leave open.
4, 5	TS0, TS1	Time-Select Pins. Set the time delay factor by connecting TS1 and TS0 to either V _{DD} or GND. See Table 1.
6	I/O	Bidirectional Interface Pin. A time delay between when the part is initiated externally by pulling I/O low and when the part subsequently pulls I/O low, is proportional to absolute temperature (°K).

M/X/W

Detailed Description

The MAX6575L/H low-cost, low-current (150µA typ) temperature sensor is ideal for interfacing with microcontrollers or microprocessors. The MAX6575L/H is a monostable, externally triggered temperature sensor that uses a Temp→Delay conversion to communicate with a µP over a single I/O line. Time-select pins (TS1, TS0) permit the internal temperature-controlled oscillator (TCO) to be scaled by four preset timeout multipliers, allowing eight separate temperature sensors to share one I/O line. Different sensors on the same I/O line will use different timeout multipliers to avoid overlapping signals.

Operating the MAX6575L/H

Figure 1 illustrates the timing for the MAX6575L/H. When the device is powered up, it assumes a ready state where it awaits an external trigger at the I/O pin. The I/O pin of the MAX6575L/H has an open-drain output structure that requires a pull-up resistor to maintain the proper logic levels. Once the I/O pin is pulled low and then released, control of the I/O pin is transferred to the MAX6575L/H. The temperature conversion begins on the falling edge of the externally triggered pulse. The I/O line is pulled low at a later time. That time is determined by the device temperature and the Time Select pins (TS1, TS0). The I/O line remains low for 5Tµs, where T is the temperature in degrees Kelvin. The temperature of the device is represented by the edgeto-edge delay of the externally triggered pulse and the falling edge of the subsequent pulse originating from the device. The device can be manually reset by pulling the I/O line low for more than tRESET (16ms max). The device will automatically reset after a maxi-

TIME-SEL	ECT PINS		ULTIPLIERS /°K)
TS1	TS0	MAX6575L	MAX6575H
GND	GND	5	160
GND	V _{DD}	20	320
V _{DD}	GND	40	480
Vdd	Vdd	80	640

Table 1. Time-Select Pin Configuration

mum delay of 520ms, at which point it will again be in a ready state awaiting a start pulse.

Definition of Terms:

- tRESET: Time I/O must be externally pulled low to guarantee the MAX6575L/H is in a ready state awaiting external trigger. (Part will assume a ready state after 520ms without a reset pulse.)
- tSETUP: Time I/O must be high prior to a start pulse.
- tstart: Trigger pulse which starts the on-chip timing sequence on its falling edge.
- tDx: Timing delay between the falling edge of the start pulse and the falling edge initiated by CHIP#x.
- t_{Lx} : I/O pulse low time (5Tµs).
- tREADY: Time after falling edge of start pulse when the MAX6575L/H will reset itself and await the next external trigger.

The temperature, in degrees Celsius, may be calculated as follows:

 $T(^{\circ}C) = [t_{Dx}(\mu s) / timeout multiplier(\mu s/^{\circ}K)] - 273.15^{\circ}K$

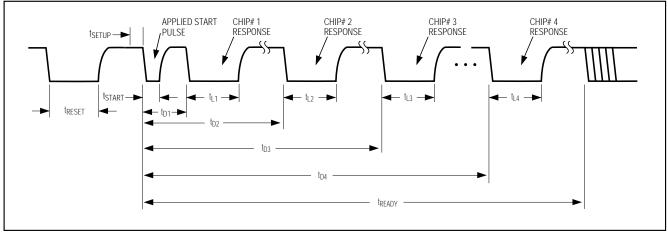


Figure 1. Timing Diagram

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		•		• •				
TIMEOUT		MAX	6575L			MAX	6575H	
MULTIPLIER	5	20	40	80	160	320	480	640
5		>165	>165	>165	>165	>165	>165	>165
20			95.5	>165	>165	>165	>165	>165
40				132.0	>165	>165	>165	>165
80					153.5	>165	>165	>165
160						>165	>165	>165
320							70.2	>165
480								37.9
640								

Table 2. Allowable Temperature Differential (°C)

Table 3. Typical Peak Noise Amplitude

		•						
PARAMETER		MAX	6575L			MAX	6575H	
Timeout Multiplier	5	20	40	80	160	320	480	640
Noise Amplitude (°C)	±0.33	±0.15	±0.15	±0.098	±0.091	±0.063	±0.043	±0.037

Time-Select Pins (TS1, TS0)

Table 1 shows the configuration of the Time-select pins for the MAX6575L/H. Each device allows four selectable timeout multipliers intended to prevent overlapping when multiple devices are used on the same I/O line. Tie TS1 and TS0 to either GND or V_{DD} to select the desired temperature multiplier.

To monitor several chips on the same I/O line, different timeout multipliers should be selected using the TS1 and TS0 pins. The timeout periods are then scaled so that the response times will not overlap (see *Timeout Selection*).

Applications Information

Timeout Selection

Under extreme temperature conditions, it is possible for an overlap to occur between the timeout delays of different sensors in a multidrop configuration. This overlap can occur only if the temperature differential recorded between two devices is very large. Timeout overlaps can be avoided in multidrop configurations by selecting the appropriate timeout multipliers. Table 2 illustrates the allowable temperature differential between devices when the maximum error is present on each device. Allowable temperature differentials greater than 165°C indicate no overlap. For example, if the maximum temperature differential in a system is 80°C, the only combinations of timeout multipliers that could result in timeout overlap would be a 320:480µs/°K (70.2°C) or a 480:640µs/°K (37.9°C) combination. As long as these combinations of timeout multipliers are not used in the same multidrop configuration, no overlap can occur. Thus, seven MAX6575L/H parts can be used in the same multidrop configuration if the maximum temperature differential between parts is 80°C. A similar analysis shows that four MAX6575L/H parts can be used when the maximum temperature differential extends over the entire 165°C range of the part.

Noise Considerations

The accuracy of the MAX6575L/H timeout delay is susceptible to noise generated both internally and externally. The effects of external noise can be minimized by placing a 0.1μ F ceramic bypass capacitor close to the device's supply pin. Internal noise is inherent in the operation of the device and is detailed in Table 3. Internal averaging minimizes the effect of this noise when using longer timeout multipliers. The effects of this noise are included in the overall accuracy of the device as specified in the *Electrical Characteristics* table.

MAX6575L/H

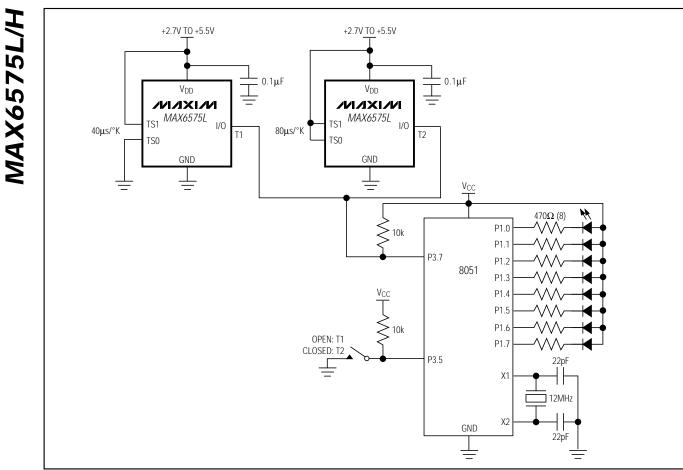


Figure 2. Interfacing Multiple Devices with a Microcontroller

Interfacing Multiple Devices with a Microcontroller

Figure 2 shows how to interface multiple MAX6575L/H devices with an 8051 microcontroller. The first device, T1, is configured for a timeout multiplier of $40\mu s/^{\circ}K$, while the second device, T2, is configured for a timeout multiplier of $80\mu s/^{\circ}K$ to avoid overlap. The microcontroller takes in temperature values from both sensors, T1 and T2, on a single port pin, P3.7. The microcontroller displays five times the temperature in degrees Celsius in binary on Port 1. A switch connected to a pull-up resistor at Port 3.5 selects which temperature is displayed: open = T1, closed = T2. Code is provided for this application as Listing 1.

Listing 1. 8051 Code Example

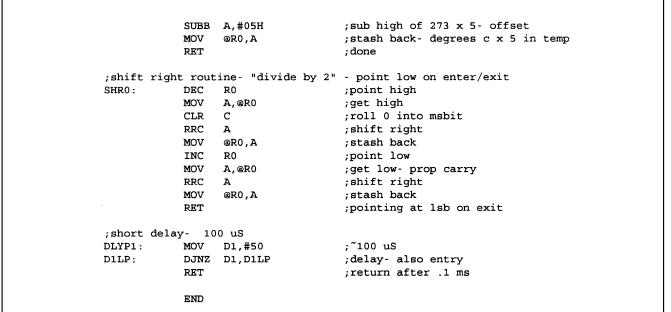
. Domonator	ation -	nd togt gods for	************************************
			MAX6575 Temp to Delay
	-		m 2 sensors on single
			up as 5 times C in binary on $L=2$
			temp displayed- H=1, L=2.
			ay 105 or 01101001 on P1
; EQUATES			
TEMP1H	EQU	10H	;TEMPERATURE 1
TEMP1L	EQU	11H	; IEMPERATORE I
TEMP2H	EQU	12H	;TEMPERATURE 2
TEMP2L		12H 13H	; IEMPERATURE 2
I EMP 2 LI	EQU	131	
D1	EQU	30H	;delay scratch registers
D2	EQU	31H	-
D3	EQU	32H	
DINC			
; PINS IOPIN	BIT	P3.7	;single pin interface
SLCT	BIT	P3.5	;select display 1/2= H/L
;MAIN			, server arbpray 1/2= 11/11
	ORG	0	;note one isr's used- timer overflow
	AJMP	BEGIN	;jump over isr's
	ORG	0BH	;timer 0 overflow- error
	CLR	TFO	;clear timer overflow
	POP	ACC	;unstack return address
	POP	ACC	;unstack return address
	PUSH		; return to top on error
	PUSH		; return to top on error
	CLR	TR0	clear timer run
	RETI		;error
	org	30h	
BEGIN:	MOV	SP,#70h	;set sp at 70H
;setup time			, <u>-</u>
,	MOV	TMOD, #01H	;t0 timer 16 bit
	MOV	IE,#82H	;enable tf0 irq- error
;			
		sure 2 temps	
DOTMP :	MOV	TH0,#0	;zero counter
	MOV	TL0,#0	;zero counter
	SETB	TRO	;start timer
	CLR	IOPIN	;write pin low- start
	CALL	DLYP1	;100 uS min low
_	SETB	IOPIN	;bring high
;do temp 1			
	MOV	R0,#TEMP1H	;point at temp1- high byte
	CALL	GTTP	;get temp1
;do temp 2			
	MOV	R0,#TEMP2H	;point at temp2- high byte
		CIIIIIID	ant tomp?
	CALL	GTTP	;get temp2

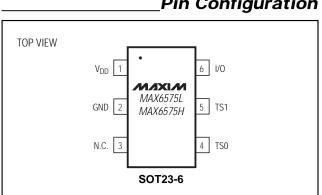
M/X/W

Listing 1. 8051 Code Example (continued)

; 2 temps are stored- display bin value of selected on P1 ; temps are 40T,80T- times are in us MOV R0,#TEMP1L ;get temp1- low byte (40T) MOV R4,#3 ;shift right 3x for 5x temp, div 8 CALL TMTOC ; convert delay to degrees C x 5 JNB P3.5,DSP2 ; if select low, display temp2 A, TEMP1L MOV ;get temperature CPL А ; invert it for active low led's MOV P1,A ;display this temp DSP2 · MOV R0,#TEMP2L ;get temp2- low byte (80T) MOV R4,#4 ;shift right 4x for 5x temp, div 16 ; convert delay to degrees C x 5 CALL TMTOC P3.5,DSP1 JB ; if select high, display temp1 above MOV A, TEMP2L ;get temperature CPL; invert it for active low led's Α MOV P1,A ;display this temp ;done ;wait for 600 ms and do it again DSP1: MOV D3,#60 DLL1: MOV D2,#100 DLL2: MOV D1,#50 ;inner loop DLLLP: DJNZ D1, DLLLP ;loop 100 us DJNZ D2, DLL2 ;loop 10 ms DJNZ D3,DLL1 ;loop 600ms JMP DOTMP ;loop forever ;subroutines ********** ;GET TEMP- main, capture timer0 to @r0 after pin low edge GTTP : IOPIN, GTTP ;wait for low- irq gets hangs JB MOV A, THO ;get high- quick MOV B,TLO ;get low- quick CJNE A, THO, ROLL ;check rollover msb JMP NOROL ;no ROLL: MOV A, THO ;get high again MOV B,TLO get low again; NOROL: MOV @R0,A ;stash msb INC RO ;point next MOV @R0,B ;stash lsb WATTH JNB IOPIN, WAITH ;wait for low- irq gets hangs RET ;sub; converts uS to degrees c x 5, R4 is # of right shifts ;shift right TMTOC : CALL SHR0 DJNZ R4, TMTOC ;loop til shifted= 5x MOV A.@R0 ;get x5 lsb CLR С ;ready for subb SUBB A,#055H ;low byte of 273 x 5- offset MOV @R0,A ;stash back DEC R0 ;point hi MOV A.@RO ;get hi- prop carry

Listing 1. 8051 Code Example (continued)





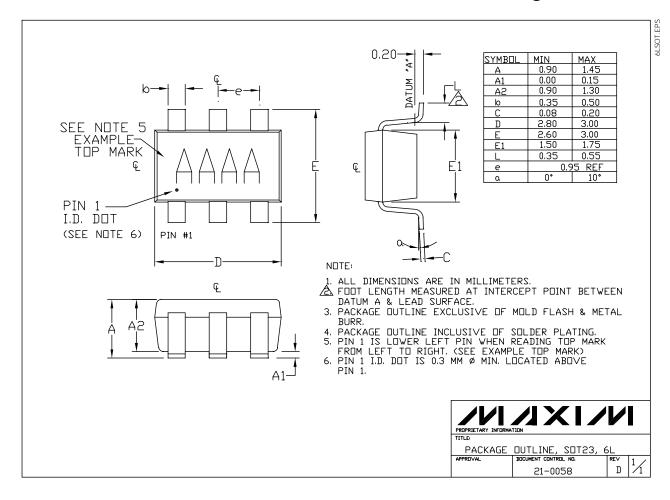
Pin Configuration

Chip Information

TRANSISTOR COUNT: 302

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Package Information



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NOTES

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NOTES

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